APPLI-TEC
THERMOSET ADHESIVE SOLUTIONS
ISO 9001 / AS9100 CERTIFIED

5108 Epoxy

Self-leveling, withstands high humidity environments

5108 is a black, electrically isolating epoxy adhesive specifically designed for potting and sealing electronic components. 5108 is a self-leveling material that exhibits low shrinkage once cured and can withstand high temperatures and high humidity or wet environments. This material is also environmentally friendly. 5108 is available in one-part pre-mixed and frozen syringes and two-part room temperature stable kits.

UNCURED	
Pot Life @ 25°C	2 hours
Viscosity, Part A @25°C	2,100 cPs
Viscosity, Part B @25°C	11,000 cPs
Viscosity, mixed @ 25°C	5,000 cPs
Shelf Life, PMF	@ -40°C 6 Months
Shelf Life, 2-Part Kit	@18°C to 25°C 12 Months
Mix Ratio	100A to 51.75B parts by weight
CURE OPTIONS	1 hour @ 92°C 4 hours @ 65°C 48 hours @ 25°C
CURED PROPERTIES	Based on cure of 4 hours @ 65°C
Color	Black
Shore D Hardness	80
Lap Shear (psi)	3500
Density (g/cc)	1.07
Glass Transition Temp (°C)	45
Shrinkage Linear (%)	0.26
ELECTRICAL PROPERTIES	Based on cure of 4 hours @ 65°C
Dielectric Constant	3.2 @ 1 kHz
Dissipation Factor	0.008 @ 1 kHz
Dielectric Strength (volts/mil)	580
Volume Resistivity (ohm-cm)	7.0E 13 @ 500 VDC
THERMAL PROPERTIES	Based on cure of 4 hours @ 65°C
Glass Transition Temp (°C)	45
Degradation Temp. (°C)	275
OUTGASSING PROPERTIES	Based on cure of 4 hours @ 65°C
TML (%)	0.75
CVCM (%)	0.01
WVR (%)	0.39
ACOUSTIC PROPERTIES	
Velocity (m/s)	2,345
Impedance (MRayls)	2.51

KEY FEATURES

- Adheres to Dissimilar Materials
- Ideal for Bonding, Potting & Encapsulation
- Self Leveling
- Hydrolytic Stability
- High Temperature Resistant
- Low Shrinkage
- **√ RoHS Compliant**

Chat with a specialist:

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Loss (dB/cm-MHz)	-4.83
Density (g/cc)	1.07